

UH130

Semi-automatic die matrix expander



HIGHLIGHTS

- ▶ No user dependent
- ▶ Easy grip ring insertion
- ▶ Expansion height adjust
- ▶ Grip ring choice

SPECIFICATIONS

- ▶ Automatic ram
- ▶ Ram speed adjust
- ▶ Thermal chuck
- ▶ Circular knife option

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Model UH130 die matrix expander defines the standard in die presentation through precise control of die separation process parameters. Better die presentation results in higher throughput and increased yield. The UH130 series facilitates this by maintaining die orientation and consistent die spacing.

The heated wafer ram is regulated by a digital temperature controller and stops at a user preset height, resulting in consistent repeatability of expansion.

The unit features a compact tabletop form factor and is extremely easy to operate. Virtually all operator variables have been eliminated.

Features

- Up to 12" wafer capability standard
- Automatic pneumatic expansion
- Adjustable speed and expansion height
- Grip ring automatic insertion
- Temperature controlled platen
- Built-in circular cutter for cutting film
- Pneumatic securing frame

Models

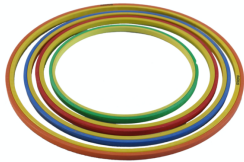
UH130-8	For wafer up to 8" (200 mm)
UH130-12	For wafer up to 12" (300 mm)

Configurations & options

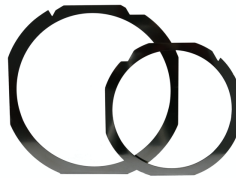
- Automatic circular cutting assembly
Tape will be cut around the grip ring to remove the frame
- Grip ring insertion head
Clamp system following grip ring size

Specifications

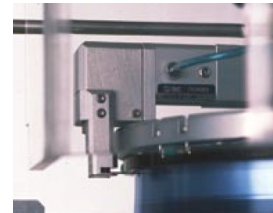
Frame holding	Clamp by air
Chuck temperature	Up to 60°C
Expansion ram style	Pneumatic
Expansion height	Adjustable up to 2.3" (58.42 mm)
Expansion speed	Adjustable
Grip ring insertion	Automatic
Tape cutting	Automatic circular knife (optional)
Power supply	240 VAC / 50 Hz / 2A (single phase)
Air	60 PSI @ 3 scfm (filtered and regulated) - 1/4" OD push in



Grip ring



Film frames



Cutting system

